



# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## 8K Microwire Compatible Serial EEPROM

Device Selection Table

Part Number	Vcc Range	ORG Pin	PE Pin	Word Size	Temp Ranges	Packages
93AA76A	1.8-5.5	No	No	8-bit	I	OT
93AA76B	1.8-5.5	No	No	16-bit	I	OT
93LC76A	2.5-5.5	No	No	8-bit	I, E	OT
93LC76B	2.5-5.5	No	No	16-bit	I, E	OT
93C76A	4.5-5.5	No	No	8-bit	I, E	OT
93C76B	4.5-5.5	No	No	16-bit	I, E	OT
93AA76C	1.8-5.5	Yes	Yes	8 or 16-bit	I	P, SN, ST, MS
93LC76C	2.5-5.5	Yes	Yes	8 or 16-bit	I, E	P, SN, ST, MS
93C76C	4.5-5.5	Yes	Yes	8 or 16-bit	I, E	P, SN, ST, MS

### Features

- Low-power CMOS technology
- ORG pin to select word size for '76C' version
- 1024 x 8-bit organization 'A' devices (no ORG)
- 512 x 16-bit organization 'B' devices (no ORG)
- Program Enable pin to write-protect the entire array (except on SOT-23 packages)
- Self-timed ERASE/WRITE cycles (including auto-erase)
- Automatic ERAL before WRAL
- Power-on/off data protection circuitry
- Industry standard 3-wire serial I/O
- Device Status signal (READY/BUSY)
- Sequential READ function
- 1,000,000 E/W cycles
- Data retention > 200 years
- Temperature ranges supported:
  - Industrial (I) -40°C to +85°C
  - Automotive (E) -40°C to +125°C

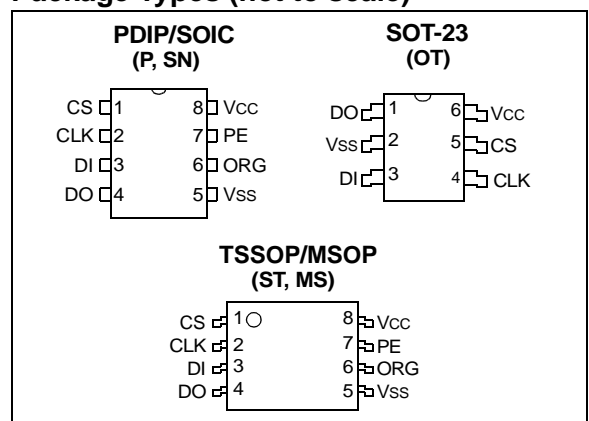
### Pin Function Table

Name	Function
CS	Chip Select
CLK	Serial Data Clock
DI	Serial Data Input
DO	Serial Data Output
Vss	Ground
PE	Program Enable
ORG	Memory Configuration
Vcc	Power Supply

### Description

The Microchip Technology Inc. 93XX76A/B/C devices are 8K bit, low-voltage, serial Electrically Erasable PROMs (EEPROM). Word-selectable devices such as the 93XX76C are dependent upon external logic levels driving the ORG pin to set word size. For dedicated 8-bit communication, the 93XX76A devices are available, while the 93XX76B devices provide dedicated 16-bit communication, available on SOT-23 devices only. A Program Enable (PE) pin allows the user to write-protect the entire memory array. Advanced CMOS technology makes these devices ideal for low-power, nonvolatile memory applications. The 93XX Series is available in standard packages including 8-lead PDIP and SOIC, and advanced packaging including 8-lead MSOP, 6-lead SOT-23, and 8-lead TSSOP. Pb-free (Pure Matte Sn) finish is also available.

### Package Types (not to scale)



# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings (†)

V <sub>CC</sub> .....	7.0V
All inputs and outputs w.r.t. V <sub>SS</sub> .....	-0.6V to V <sub>CC</sub> +1.0V
Storage temperature .....	-65°C to +150°C
Ambient temperature with power applied.....	-40°C to +125°C
ESD protection on all pins .....	≥ 4 kV

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

**TABLE 1-1: DC CHARACTERISTICS**

All parameters apply over the specified ranges unless otherwise noted.				V <sub>CC</sub> = 1.8V to 5.5V Industrial (I): TA = -40°C to +85°C Automotive (E): TA = -40°C to +125°C			
Param. No.	Symbol	Parameter	Min	Typ	Max	Units	Conditions
D1	V <sub>IH1</sub>	High-level input voltage	2.0	—	V <sub>CC</sub> +1	V	V <sub>CC</sub> ≥ 2.7V
	V <sub>IH2</sub>		0.7 V <sub>CC</sub>	—	V <sub>CC</sub> +1	V	V <sub>CC</sub> < 2.7V
D2	V <sub>IL1</sub>	Low-level input voltage	-0.3	—	0.8	V	V <sub>CC</sub> ≥ 2.7V
	V <sub>IL2</sub>		-0.3	—	0.2 V <sub>CC</sub>	V	V <sub>CC</sub> < 2.7V
D3	V <sub>OL1</sub>	Low-level output voltage	—	—	0.4	V	I <sub>OL</sub> = 2.1 mA, V <sub>CC</sub> = 4.5V
	V <sub>OL2</sub>		—	—	0.2	V	I <sub>OL</sub> = 100 μA, V <sub>CC</sub> = 2.5V
D4	V <sub>OH1</sub>	High-level output voltage	2.4	—	—	V	I <sub>OH</sub> = -400 μA, V <sub>CC</sub> = 4.5V
	V <sub>OH2</sub>		V <sub>CC</sub> - 0.2	—	—	V	I <sub>OH</sub> = -100 μA, V <sub>CC</sub> = 2.5V
D5	I <sub>LI</sub>	Input leakage current	—	—	±1	μA	V <sub>IN</sub> = V <sub>SS</sub> to V <sub>CC</sub>
D6	I <sub>LO</sub>	Output leakage current	—	—	±1	μA	V <sub>OUT</sub> = V <sub>SS</sub> to V <sub>CC</sub>
D7	C <sub>IN</sub> , C <sub>OUT</sub>	Pin capacitance (all inputs/ outputs)	—	—	7	pF	V <sub>IN</sub> /V <sub>OUT</sub> = 0V ( <b>Note 1</b> ) TA = 25°C, F <sub>CLK</sub> = 1 MHz
D8	I <sub>CC</sub> write	Write current	—	—	3	mA	F <sub>CLK</sub> = 3 MHz, V <sub>CC</sub> = 5.5V
			—	500	—	μA	F <sub>CLK</sub> = 2 MHz, V <sub>CC</sub> = 2.5V
D9	I <sub>CC</sub> read	Read current	—	—	1	mA	F <sub>CLK</sub> = 3 MHz, V <sub>CC</sub> = 5.5V
			—	—	500	μA	F <sub>CLK</sub> = 2 MHz, V <sub>CC</sub> = 3.0V
			—	100	—	μA	F <sub>CLK</sub> = 2 MHz, V <sub>CC</sub> = 2.5V
D10	I <sub>CCS</sub>	Standby current	—	—	1	μA	I – Temp
			—	—	5	μA	E – Temp CLK = Cs = 0V ORG = DI = V <sub>SS</sub> or V <sub>CC</sub> ( <b>Note 2</b> ) ( <b>Note 3</b> )
D11	V <sub>POR</sub>	V <sub>CC</sub> voltage detect 93AA76A/B/C, 93LC76A/B/C 93C76A/B/C	—	1.5V	—	V	(Note 1)
			—	3.8V	—	V	

**Note 1:** This parameter is periodically sampled and not 100% tested.

**2:** ORG pin not available on ‘A’ or ‘B’ versions.

**3:** READY/BUSY status must be cleared from DO, see **Section 3.4 “Data Out (DO)”**.

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

**TABLE 1-2: AC CHARACTERISTICS**

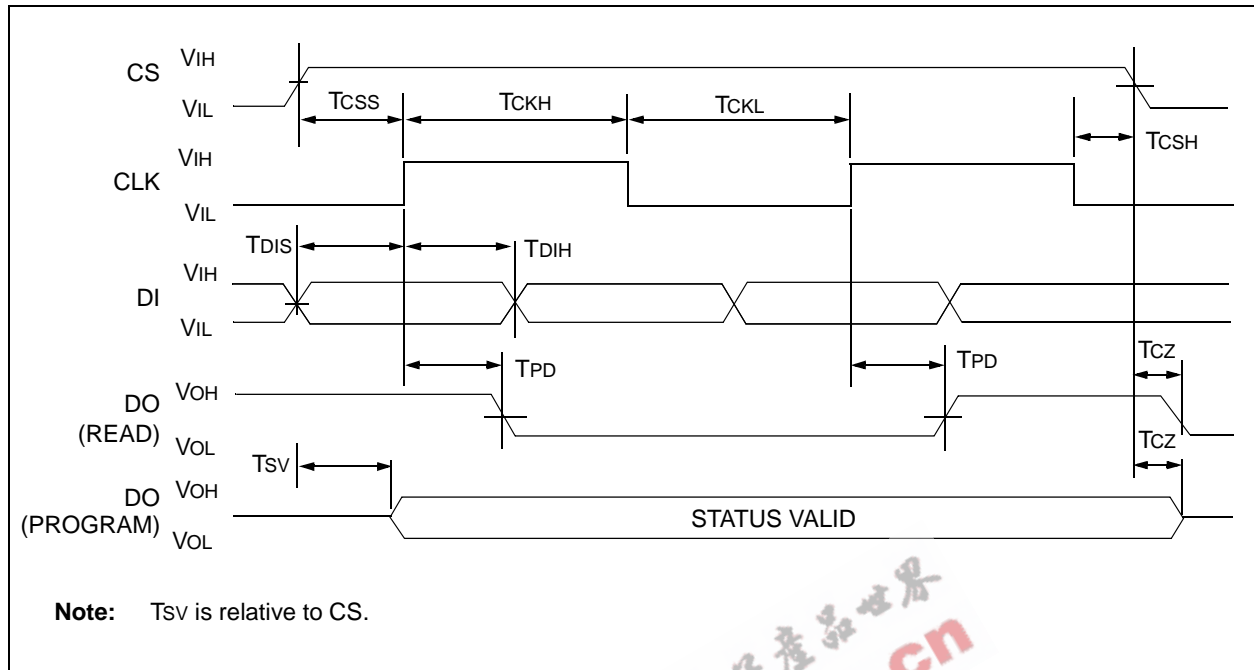
All parameters apply over the specified ranges unless otherwise noted.			VCC = 1.8V to 5.5V Industrial (I): TA = -40°C to +85°C Automotive (E): TA = -40°C to +125°C			
Param. No.	Symbol	Parameter	Min	Max	Units	Conditions
A1	FCLK	Clock frequency	—	3 2 1	MHz MHz MHz	4.5V ≤ VCC < 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
A2	TCKH	Clock high time	200 250 450	—	ns ns ns	4.5V ≤ VCC < 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
A3	TCKL	Clock low time	100 200 450	—	ns ns ns	4.5V ≤ VCC < 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
A4	TCSS	Chip Select setup time	50 100 250	—	ns ns ns	4.5V ≤ VCC < 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
A5	TCSH	Chip Select hold time	0	—	ns	1.8V ≤ VCC < 5.5V
A6	TCSL	Chip Select low time	250	—	ns	1.8V ≤ VCC < 5.5V
A7	TDIS	Data input setup time	50 100 250	—	ns ns ns	4.5V ≤ VCC < 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
A8	TDIH	Data input hold time	50 100 250	—	ns ns ns	4.5V ≤ VCC < 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
A9	TPD	Data output delay time	—	100 250 400	ns ns ns	4.5V ≤ VCC < 5.5V, CL = 100 pF 2.5V ≤ VCC < 4.5V, CL = 100 pF 1.8V ≤ VCC < 2.5V, CL = 100 pF
A10	TCZ	Data output disable time	—	100 200	ns ns	4.5V ≤ VCC < 5.5V, (Note 1) 1.8V ≤ VCC < 4.5V, (Note 1)
A11	Tsv	Status valid time	—	200 300 500	ns ns ns	4.5V ≤ VCC < 5.5V, CL = 100 pF 2.5V ≤ VCC < 4.5V, CL = 100 pF 1.8V ≤ VCC < 2.5V, CL = 100 pF
A12	TWC	Program cycle time	—	5	ms	Erase/Write mode (AA and LC versions)
A13	TWC		—	2	ms	Erase/Write mode (93C versions)
A14	TEC		—	6	ms	ERAL mode, 4.5V ≤ VCC ≤ 5.5V
A15	TWL		—	15	ms	WRAL mode, 4.5V ≤ VCC ≤ 5.5V
A16	—	Endurance	1M	—	cycles	25°C, VCC = 5.0V, (Note 2)

**Note 1:** This parameter is periodically sampled and not 100% tested.

**2:** This application is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which may be obtained from [www.microchip.com](http://www.microchip.com).

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

**FIGURE 1-1: SYNCHRONOUS DATA TIMING**



**TABLE 1-3: INSTRUCTION SET FOR X 16 ORGANIZATION (93XX76B OR 93XX76C WITH ORG = 1)**

Instruction	SB	Opcode	Address	Data In	Data Out	Req. CLK Cycles
READ	1	10	X A8 A7 A6 A5 A4 A3 A2 A1 A0	—	D15 – D0	29
EWEN	1	00	1 1 X X X X X X X X X X	—	HIGH-Z	13
ERASE	1	11	X A8 A7 A6 A5 A4 A3 A2 A1 A0	—	(RDY/ $\overline{BSY}$ )	13
ERAL	1	00	1 0 X X X X X X X X X X	—	(RDY/ $\overline{BSY}$ )	13
WRITE	1	01	X A8 A7 A6 A5 A4 A3 A2 A1 A0	D15 – D0	(RDY/ $\overline{BSY}$ )	29
WRAL	1	00	0 1 X X X X X X X X X X	D15 – D0	(RDY/ $\overline{BSY}$ )	29
EWDS	1	00	0 0 X X X X X X X X X X	—	HIGH-Z	13

**TABLE 1-4: INSTRUCTION SET FOR X 8 ORGANIZATION (93XX76A OR 93XX76C WITH ORG = 0)**

Instruction	SB	Opcode	Address	Data In	Data Out	Req. CLK Cycles
READ	1	10	X A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	—	D7 – D0	22
EWEN	1	00	1 1 X X X X X X X X X X	—	HIGH-Z	14
ERASE	1	11	X A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	—	(RDY/ $\overline{BSY}$ )	14
ERAL	1	00	1 0 X X X X X X X X X X	—	(RDY/ $\overline{BSY}$ )	14
WRITE	1	01	X A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	D7 – D0	(RDY/ $\overline{BSY}$ )	22
WRAL	1	00	0 1 X X X X X X X X X X	D7 – D0	(RDY/ $\overline{BSY}$ )	22
EWDS	1	00	0 0 X X X X X X X X X X	—	HIGH-Z	14

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## 2.0 FUNCTIONAL DESCRIPTION

When the ORG\* pin is connected to VCC, the (x16) organization is selected. When it is connected to ground, the (x8) organization is selected. Instructions, addresses and write data are clocked into the DI pin on the rising edge of the clock (CLK). The DO pin is normally held in a HIGH-Z state except when reading data from the device, or when checking the READY/BUSY status during a programming operation. The READY/BUSY status can be verified during an Erase/Write operation by polling the DO pin; DO low indicates that programming is still in progress, while DO high indicates the device is ready. DO will enter the HIGH-Z state on the falling edge of CS.

### 2.1 Start Condition

The Start bit is detected by the device if CS and DI are both high with respect to the positive edge of CLK for the first time.

Before a Start condition is detected, CS, CLK and DI may change in any combination (except to that of a Start condition), without resulting in any device operation (READ, WRITE, ERASE, EWEN, EWDS, ERAL or WRAL). As soon as CS is high, the device is no longer in Standby mode.

An instruction following a Start condition will only be executed if the required opcode, address and data bits for any particular instruction are clocked in.

### 2.2 Data In/Data Out (DI/DO)

It is possible to connect the Data In and Data Out pins together. However, with this configuration it is possible for a "bus conflict" to occur during the "dummy zero" that precedes the read operation, if A0 is a logic high-level. Under such a condition the voltage level seen at Data Out is undefined and will depend upon the relative impedances of Data Out and the signal source driving A0. The higher the current sourcing capability of the driver, the higher the voltage at the Data Out pin. In order to limit this current, a resistor should be connected between DI and DO.

### 2.3 Data Protection

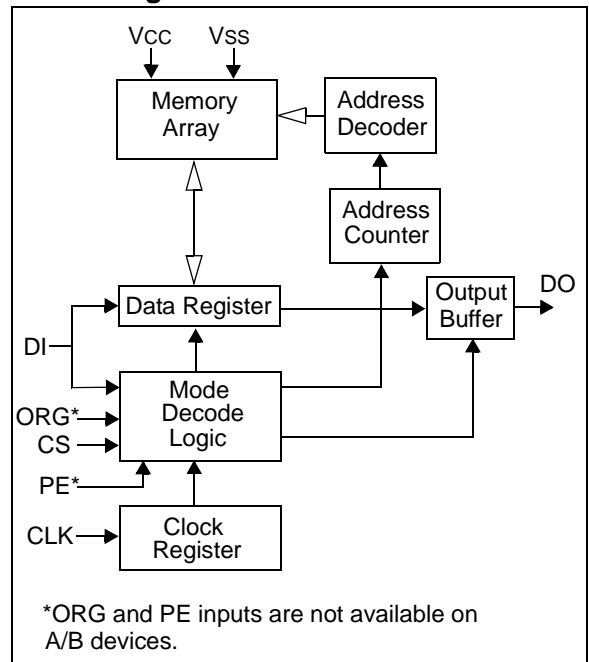
All modes of operation are inhibited when VCC is below a typical voltage of 1.5V for '93AA' and '93LC' devices or 3.8V for '93C' devices.

The EWEN and EWDS commands give additional protection against accidentally programming during normal operation.

**Note:** For added protection, an EWDS command should be performed after every write operation.

After power-up, the device is automatically in the EWDS mode. Therefore, an EWEN instruction must be performed before the initial ERASE or WRITE instruction can be executed.

### Block Diagram



# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

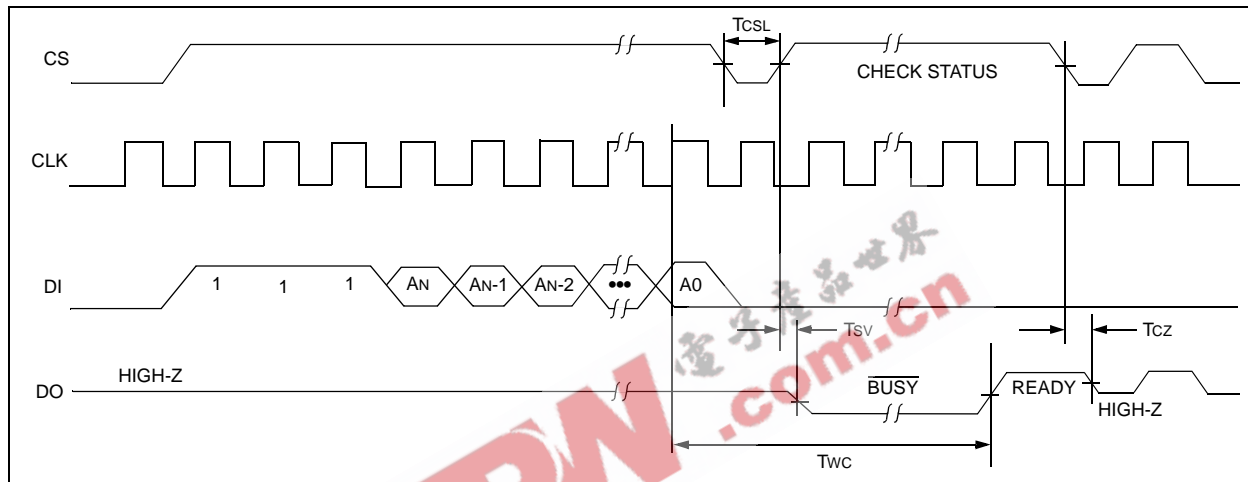
## 2.4 ERASE

The **ERASE** instruction forces all data bits of the specified address to the logical '1' state. The rising edge of CLK before the last address bit initiates the write cycle.

The DO pin indicates the **READY/BUSY** status of the device if CS is brought high after a minimum of 250 ns low ( $T_{CSL}$ ). DO at logical '0' indicates that programming is still in progress. DO at logical '1' indicates that the register at the specified address has been erased and the device is ready for another instruction.

**Note:** Issuing a Start bit and then taking CS low will clear the **READY/BUSY** status from DO.

**FIGURE 2-1: ERASE TIMING**



# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## 2.5 ERASE ALL (ERAL)

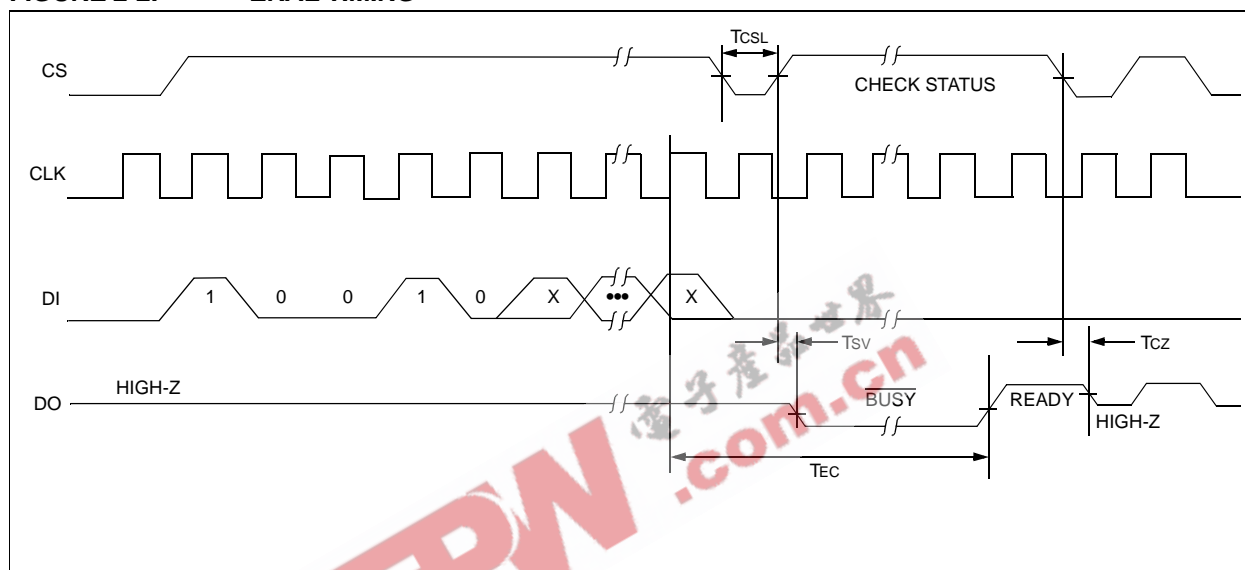
The Erase All (ERAL) instruction will erase the entire memory array to the logical '1' state. The ERAL cycle is identical to the ERASE cycle, except for the different opcode. The ERAL cycle is completely self-timed. The rising edge of CLK before the last data bit initiates the write cycle. Clocking of the CLK pin is not necessary after the device has entered the ERAL cycle.

The DO pin indicates the READY/ $\overline{\text{BUSY}}$  status of the device, if CS is brought high after a minimum of 250 ns low ( $T_{\text{CSL}}$ ).

**Note:** Issuing a Start bit and then taking CS low will clear the READY/ $\overline{\text{BUSY}}$  status from DO.

VCC must be  $\geq 4.5\text{V}$  for proper operation of ERAL.

FIGURE 2-2: ERAL TIMING







# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

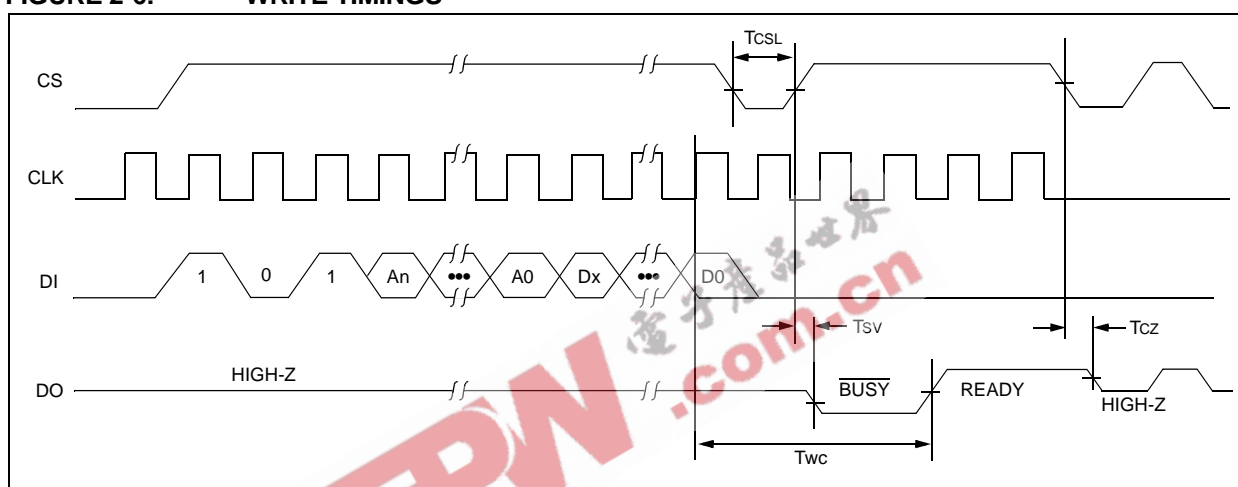
## 2.8 WRITE

The **WRITE** instruction is followed by 8 bits (If ORG is low or A-version devices) or 16 bits (If ORG pin is high or B-version devices) of data which are written into the specified address. The self-timed auto-erase and programming cycle is initiated by the rising edge of CLK on the last data bit.

The DO pin indicates the  $\overline{\text{READY}}/\overline{\text{BUSY}}$  status of the device, if CS is brought high after a minimum of 250 ns low ( $T_{\text{CSL}}$ ). DO at logical '0' indicates that programming is still in progress. DO at logical '1' indicates that the register at the specified address has been written with the data specified and the device is ready for another instruction.

**Note:** Issuing a Start bit and then taking CS low will clear the  $\overline{\text{READY}}/\overline{\text{BUSY}}$  status from DO.

FIGURE 2-6: WRITE TIMINGS



# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## 2.9 WRITE ALL (WRAL)

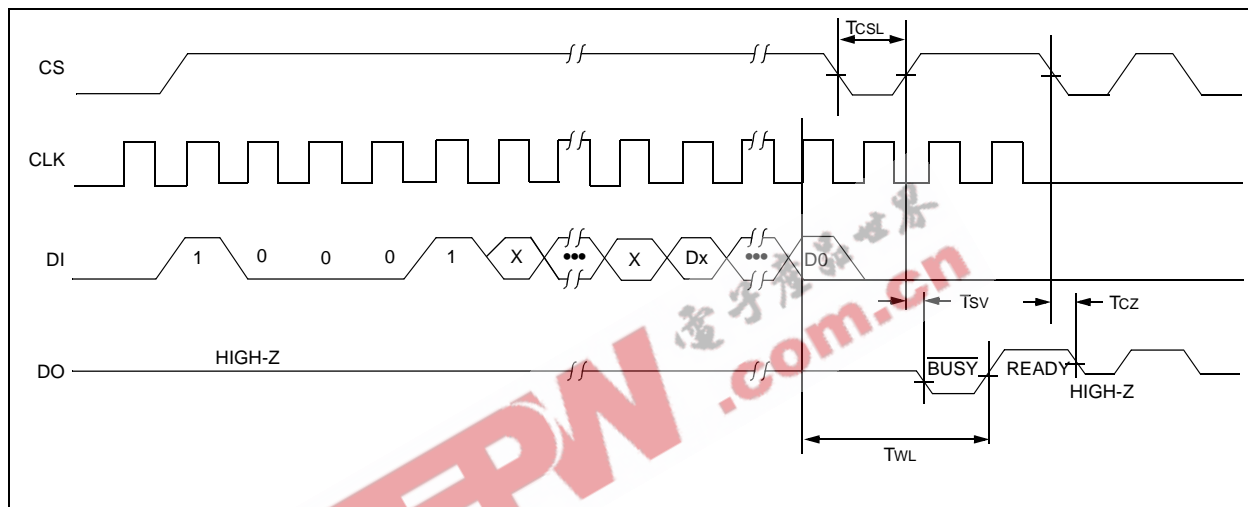
The Write All (WRAL) instruction will write the entire memory array with the data specified in the command. The self-timed auto-erase and programming cycle is initiated by the rising edge of CLK on the last data bit. Clocking of the CLK pin is not necessary after the device has entered the WRAL cycle. The WRAL command does include an automatic ERAL cycle for the device. Therefore, the WRAL instruction does not require an ERAL instruction but the chip must be in the EWEN status.

The DO pin indicates the READY/ $\overline{\text{BUSY}}$  status of the device if CS is brought high after a minimum of 250 ns low ( $T_{\text{CSL}}$ ).

**Note:** Issuing a Start bit and then taking CS low will clear the READY/ $\overline{\text{BUSY}}$  status from DO.

VCC must be  $\geq 4.5\text{V}$  for proper operation of WRAL.

FIGURE 2-7: WRAL TIMING



# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## 3.0 PIN DESCRIPTIONS

TABLE 3-1: PIN DESCRIPTIONS

Name	SOIC/PDIP/MSOP/ TSSOP	SOT-23	Function
CS	1	5	Chip Select
CLK	2	4	Serial Clock
DI	3	3	Data In
DO	4	1	Data Out
Vss	5	2	Ground
ORG	6	N/A	Organization / 93XX76C
PE	7	N/A	Program Enable
Vcc	8	6	Power Supply

### 3.1 Chip Select (CS)

A high level selects the device; a low level deselects the device and forces it into Standby mode. However, a programming cycle which is already in progress will be completed, regardless of the Chip Select (CS) input signal. If CS is brought low during a program cycle, the device will go into Standby mode as soon as the programming cycle is completed.

CS must be low for 250 ns minimum ( $T_{CSL}$ ) between consecutive instructions. If CS is low, the internal control logic is held in a Reset status.

### 3.2 Serial Clock (CLK)

The Serial Clock is used to synchronize the communication between a master device and the 93XX series device. Opcodes, address and data bits are clocked in on the positive edge of CLK. Data bits are also clocked out on the positive edge of CLK.

CLK can be stopped anywhere in the transmission sequence (at high or low-level) and can be continued anytime with respect to clock high time ( $T_{CKH}$ ) and clock low time ( $T_{CKL}$ ). This gives the controlling master freedom in preparing opcode, address and data.

CLK is a "don't care" if CS is low (device deselected). If CS is high, but the Start condition has not been detected ( $DI = 0$ ), any number of clock cycles can be received by the device without changing its status (i.e., waiting for a Start condition).

CLK cycles are not required during the self-timed WRITE (i.e., auto ERASE/WRITE) cycle.

After detection of a Start condition the specified number of clock cycles (respectively low to high transitions of CLK) must be provided. These clock cycles are required to clock in all required opcode, address and data bits before an instruction is executed. CLK and DI then become don't care inputs waiting for a new Start condition to be detected.

### 3.3 Data In (DI)

Data In (DI) is used to clock in a Start bit, opcode, address and data synchronously with the CLK input.

### 3.4 Data Out (DO)

Data Out (DO) is used in the Read mode to output data synchronously with the CLK input ( $T_{PD}$  after the positive edge of CLK).

This pin also provides  $READY/\overline{BUSY}$  status information during ERASE and WRITE cycles.  $READY/\overline{BUSY}$  status information is available on the DO pin if CS is brought high after being low for minimum Chip Select low time ( $T_{CSL}$ ) and an erase or write operation has been initiated.

The Status signal is not available on DO, if CS is held low during the entire ERASE or WRITE cycle. In this case, DO is in the HIGH-Z mode. If status is checked after the ERASE/WRITE cycle, the data line will be high to indicate the device is ready.

**Note:** Issuing a Start bit and then taking CS low will clear the  $READY/\overline{BUSY}$  status from DO.

### 3.5 Organization (ORG)

When the ORG pin is connected to VCC or Logic HI, the (x16) memory organization is selected. When the ORG pin is tied to VSS or Logic LO, the (x8) memory organization is selected. For proper operation, ORG must be tied to a valid logic level.

93XX76A devices are always x8 organization and 93XX76B devices are always x16 organization.

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

---

## 3.6 Program Enable (PE)

This pin allows the user to enable or disable the ability to write data to the memory array. If the PE pin is tied to Vcc, the device can be programmed. If the PE pin is tied to Vss, programming will be inhibited. PE is not available on 93XX76A or 93XX76B. On those devices, programming is always enabled. This pin cannot be floated, it must be tied to Vcc or Vss.

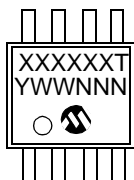
EEPW 電子產品世界  
.com.cn

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

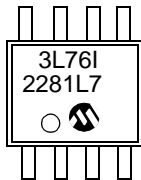
## 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

8-Lead MSOP (150 mil)



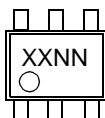
Example:



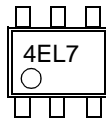
MSOP 1st Line Marking Codes		
Device	std mark	Pb-free mark
93AA76C	3A76CT	GA76CT
93LC76C	3L76CT	GL76CT
93C76C	3C76CT	GC76CT

T = blank for commercial, "I" for Industrial, "E" for Extended.

6-Lead SOT-23



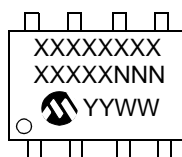
Example:



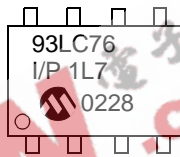
SOT23 Marking Codes		
Device	I-temp	E-temp
93AA76A	4BNN	—
93AA76B	4LNN	—
93LC76A	4ENN	4FNN
93LC76B	4PNN	4RNN
93C76A	4HNN	4JNN
93C76B	4TNN	4UNN

Pb-free topside mark is same; Pb-free noted only on carton label.

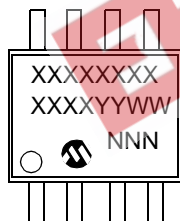
8-Lead PDIP



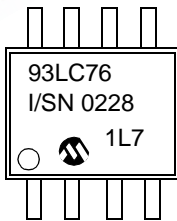
Example:



8-Lead SOIC



Example:



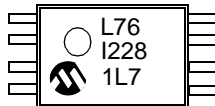
TSSOP 1st Line Marking Codes		
Device	std mark	Pb-free mark
93AA76C	A76C	GADC
93LC76C	L76C	GLDC
93C76C	C76C	GCDC

Temperature grade is marked on line 2.

8-Lead TSSOP



Example:

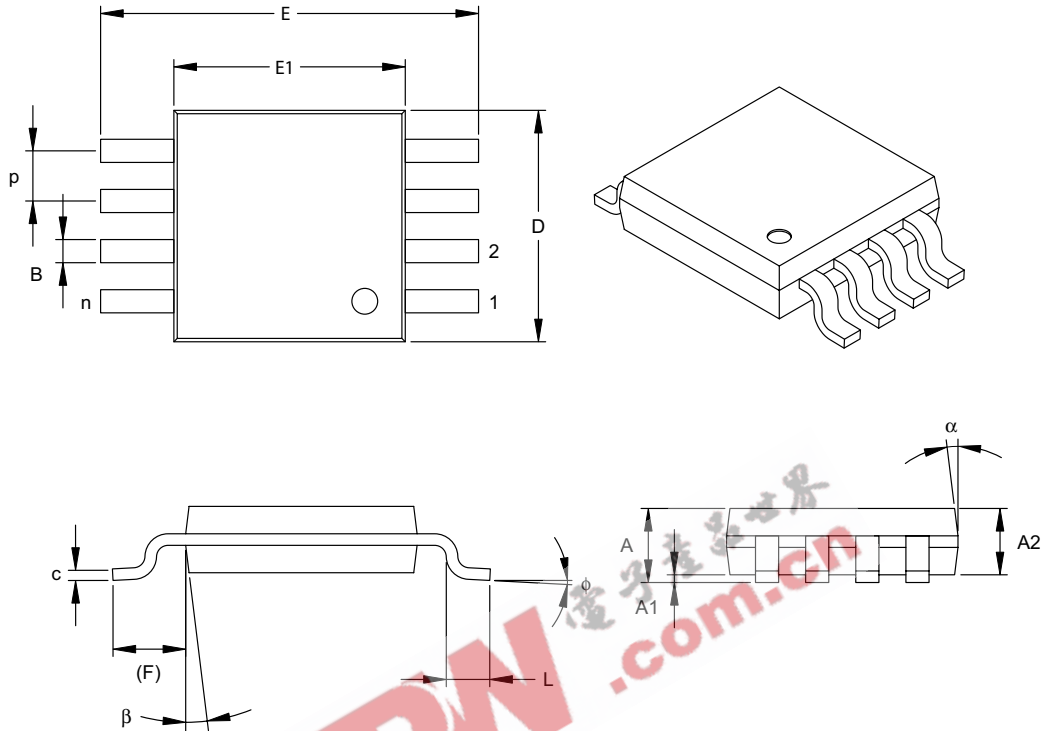


<b>Legend:</b>	XX...X	Part number
	T	Temperature
	Blank	Commercial
	I	Industrial
	E	Extended
	YY	Year code (last 2 digits of calendar year) except TSSOP and MSOP which use only the last 1 digit
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code

**Note:** Custom marking available.

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## 8-Lead Plastic Micro Small Outline Package (MS) (MSOP)



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.026 BSC			0.65 BSC	
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E		.193 TYP.			4.90 BSC	
Molded Package Width	E1		.118 BSC			3.00 BSC	
Overall Length	D		.118 BSC			3.00 BSC	
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F		.037 REF			0.95 REF	
Foot Angle	φ	0°	-	8°	0°	-	8°
Lead Thickness	c	.003	.006	.009	0.08	-	0.23
Lead Width	B	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	α	5°	-	15°	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°	5°	-	15°

\*Controlling Parameter

Notes:

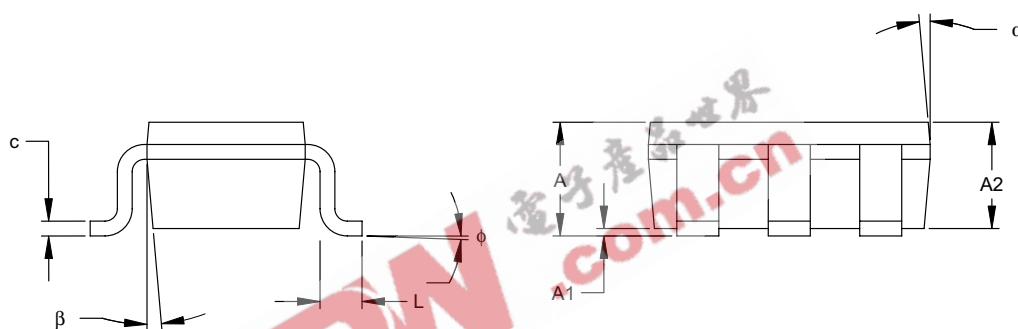
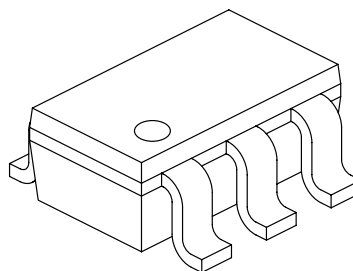
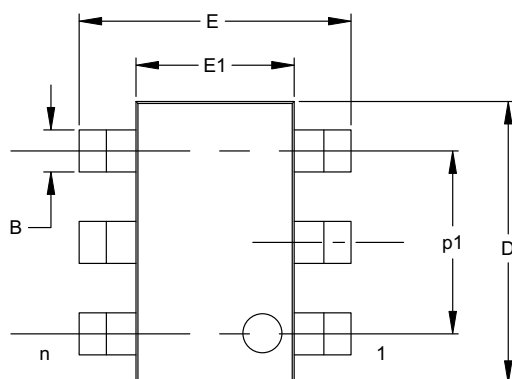
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## 6-Lead Plastic Small Outline Transistor (OT) (SOT-23)



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		6			6	
Pitch	p		.038			0.95	
Outside lead pitch (basic)	p1		.075			1.90	
Overall Height	A	.035	.046	.057	0.90	1.18	1.45
Molded Package Thickness	A2	.035	.043	.051	0.90	1.10	1.30
Standoff	A1	.000	.003	.006	0.00	0.08	0.15
Overall Width	E	.102	.110	.118	2.60	2.80	3.00
Molded Package Width	E1	.059	.064	.069	1.50	1.63	1.75
Overall Length	D	.110	.116	.122	2.80	2.95	3.10
Foot Length	L	.014	.018	.022	0.35	0.45	0.55
Foot Angle	φ	0	5	10	0	5	10
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.014	.017	.020	0.35	0.43	0.50
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

\*Controlling Parameter

Notes:

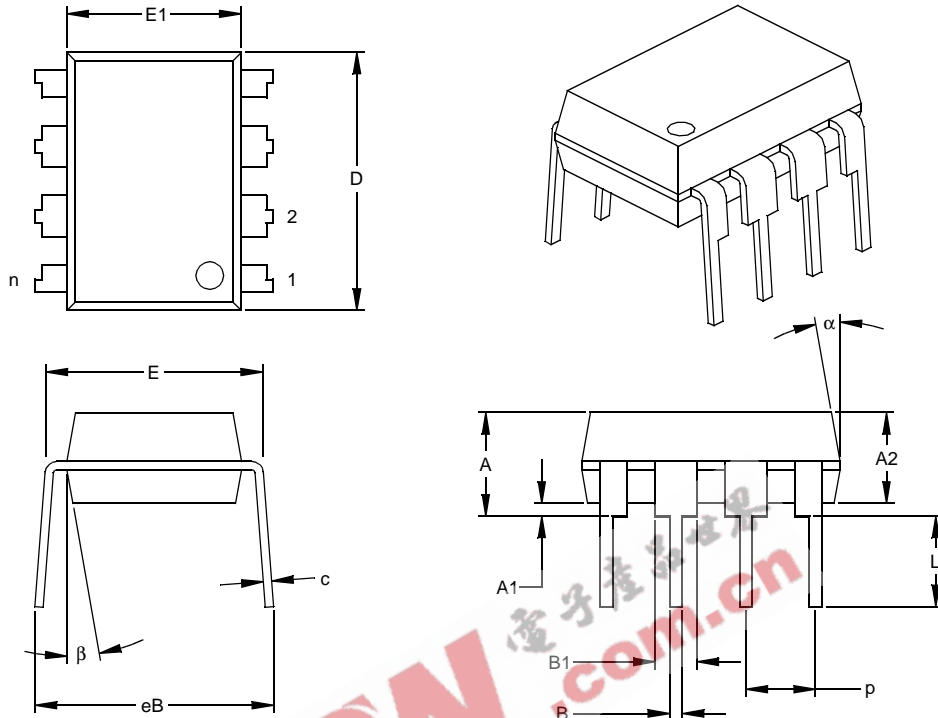
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEITA (formerly EIAJ) equivalent: SC-74A

Drawing No. C04-120

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

8-Lead Plastic Du8-Lead Plastic Small Outline (al In-line (P) – 300 mil (PDIP)



Dimension	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

\* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

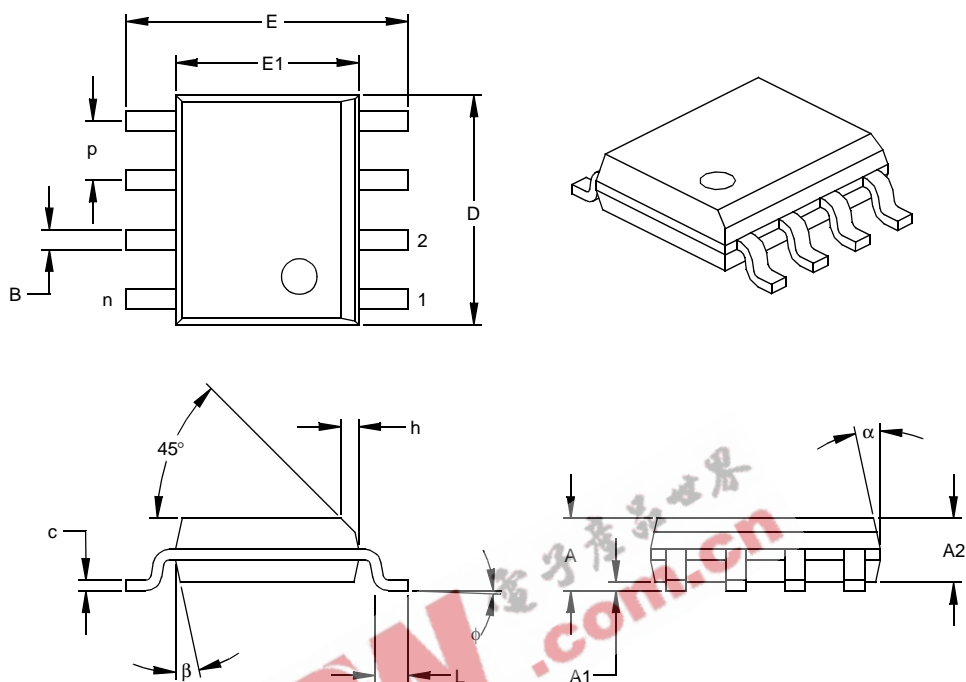
JEDEC Equivalent: MS-001

Drawing No. C04-018



# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

\* Controlling Parameter  
§ Significant Characteristic

Notes:

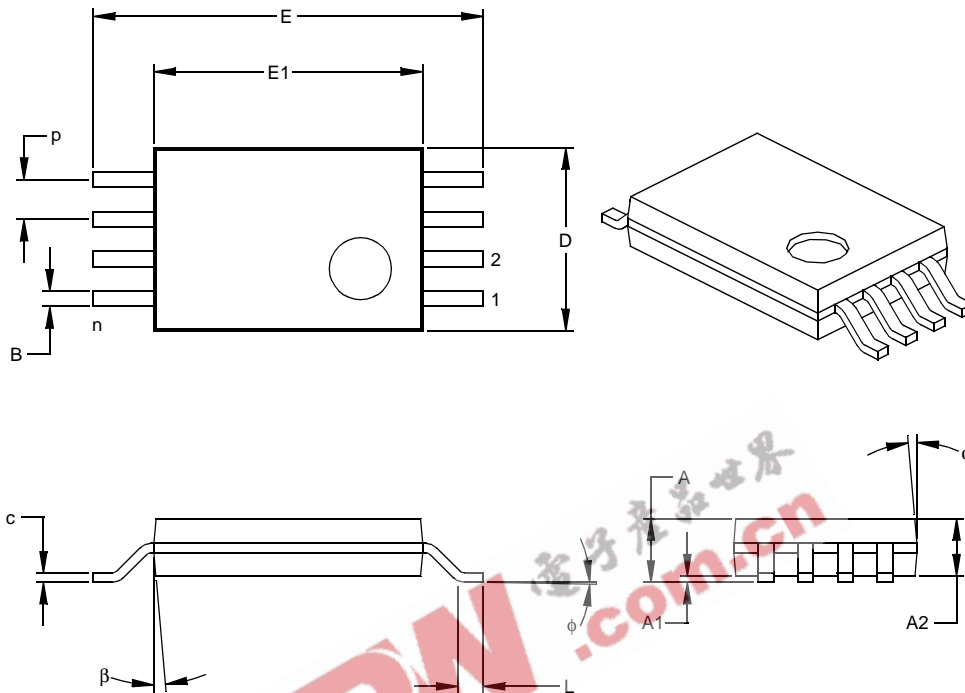
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm (TSSOP)



Dimension	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.026			0.65	
Overall Height	A			.043			1.10
Molded Package Thickness	A2	.033	.035	.037	0.85	0.90	0.95
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Overall Width	E	.246	.251	.256	6.25	6.38	6.50
Molded Package Width	E1	.169	.173	.177	4.30	4.40	4.50
Molded Package Length	D	.114	.118	.122	2.90	3.00	3.10
Foot Length	L	.020	.024	.028	0.50	0.60	0.70
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.010	.012	0.19	0.25	0.30
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

\* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEDEC Equivalent: MO-153

Drawing No. C04-086

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

---

## APPENDIX A: REVISION HISTORY

### Revision C

Corrections to Section 1.0, Electrical Characteristics.  
Section 4.1, 6-Lead SOT-23 package to OT.

### Revision D

Corrections to Device Selection Table, Table 1-1, Table 1-2, Section 2.4, Section 2.5, Section 2.8 and Section 2.9. Added note to Figure 2-7.

EEPW 電子產品世界  
.com.cn

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

---

NOTES:

EEPW 电子產品世界  
.com.cn

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

---

## ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape® or Microsoft® Internet Explorer. Files are also available for FTP download from our FTP site.

### Connecting to the Microchip Internet Web Site

The Microchip web site is available at the following URL:

**[www.microchip.com](http://www.microchip.com)**

The file transfer site is available by using an FTP service to connect to:

**<ftp://ftp.microchip.com>**

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

- Latest Microchip Press Releases
- Technical Support Section with Frequently Asked Questions
- Design Tips
- Device Errata
- Job Postings
- Microchip Consultant Program Member Listing
- Links to other useful web sites related to Microchip Products
- Conferences for products, Development Systems, technical information and more
- Listing of seminars and events

## SYSTEMS INFORMATION AND UPGRADE HOT LINE

The Systems Information and Upgrade Line provides system users a listing of the latest versions of all of Microchip's development systems software products. Plus, this line provides information on how customers can receive the most current upgrade kits. The Hot Line Numbers are:

1-800-755-2345 for U.S. and most of Canada, and

1-480-792-7302 for the rest of the world.

042003

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

---

## READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

To: Technical Publications Manager  
RE: Reader Response  
From: Name \_\_\_\_\_  
Company \_\_\_\_\_  
Address \_\_\_\_\_  
City / State / ZIP / Country \_\_\_\_\_  
Telephone: (\_\_\_\_\_) \_\_\_\_\_ - \_\_\_\_\_ FAX: (\_\_\_\_\_) \_\_\_\_\_ - \_\_\_\_\_

Application (optional):

Would you like a reply? \_\_\_Y \_\_\_N

Device: 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C Literature Number: DS21796D

Questions:

1. What are the best features of this document?

\_\_\_\_\_  
\_\_\_\_\_

2. How does this document meet your hardware and software development needs?

\_\_\_\_\_  
\_\_\_\_\_

3. Do you find the organization of this document easy to follow? If not, why?

\_\_\_\_\_  
\_\_\_\_\_

4. What additions to the document do you think would enhance the structure and subject?

\_\_\_\_\_  
\_\_\_\_\_

5. What deletions from the document could be made without affecting the overall usefulness?

\_\_\_\_\_  
\_\_\_\_\_

6. Is there any incorrect or misleading information (what and where)?

\_\_\_\_\_  
\_\_\_\_\_

7. How would you improve this document?

\_\_\_\_\_  
\_\_\_\_\_

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>X</u>	<u>/XX</u>	<u>X</u>
Device	Tape & Reel	Temperature Range	Package	Lead Finish
Device	93AA76A: 8K 1.8V Microwire Serial EEPROM (x8) 93AA76B: 8K 1.8V Microwire Serial EEPROM (x16) 93AA76C: 8K 1.8V Microwire Serial EEPROM w/ORG  93LC76A: 8K 2.5V Microwire Serial EEPROM (x8) 93LC76B: 8K 2.5V Microwire Serial EEPROM (x16) 93LC76C: 8K 2.5V Microwire Serial EEPROM w/ORG  93C76A: 8K 5.0V Microwire Serial EEPROM (x8) 93C76B: 8K 5.0V Microwire Serial EEPROM (x16) 93C76C: 8K 5.0V Microwire Serial EEPROM w/ORG			
Tape & Reel:	Blank = Standard pinout T = Tape & Reel			
Temperature Range	I = -40°C to +85°C E = -40°C to +125°C			
Package	MS = Plastic MSOP (Micro Small outline, 8-lead) OT = SOT-23, 6-lead (Tape & Reel only) P = Plastic DIP (300 mil body), 8-lead SN = Plastic SOIC (150 mil body), 8-lead ST = TSSOP, 8-lead			
Lead Finish:	Blank = Standard 63% / 37% SnPb G = Pb-free (Matte Tin - Pure Sn)			

Examples:  
a) 93AA76C-I/MS: 8K, 1024x8 or 512x16 Serial EEPROM, MSOP package, 1.8V  
b) 93AA76AT-I/OT: 8K, 1024x8 Serial EEPROM, SOT-23 package, tape and reel, 1.8V  
c) 93AA76CT-I/MS: 8K, 1024x8 or 512x16 Serial EEPROM, MSOP package, tape and reel, 1.8V  
  
a) 93LC76C-I/MS: 8K, 1024x8 or 512x16 Serial EEPROM, MSOP package, 2.5V  
b) 93LC76BT-I/OT: 8K, 512x16 Serial EEPROM, SOT-23 package, tape and reel, 2.5V  
c) 93LC76CXT-I/SNG: 8K, 1024x8 or 512x16 Serial EEPROM, SOIC package, Industrial temperature, tape and reel, Pb-free finish, 2.5V  
  
a) 93C76C-I/MS: 8K, 1024x8 or 512x16 Serial EEPROM, MSOP package, 5.0V  
b) 93C76AT-I/OT: 8K, 1024x8 Serial EEPROM, SOT-23 package, tape and reel, 5.0V

## Sales and Support

### Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site ([www.microchip.com](http://www.microchip.com))

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

### New Customer Notification System

Register on our web site ([www.microchip.com/cn](http://www.microchip.com/cn)) to receive the most current information on our products.

# 93AA76A/B/C, 93LC76A/B/C, 93C76A/B/C

---

NOTES:

EEPW 电子產品世界  
.com.cn



---

---

**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

---

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

**Trademarks**

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, KEELOQ, MPLAB, PIC, PICmicro, PICSTART, PRO MATE and PowerSmart are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.


Amplab, FilterLab, microID, MXDEV, MXLAB, PICMASTER, SEEVAL, SmartShunt and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Application Maestro, dsPICDEM, dsPICDEM.net, dsPICworks, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, microPort, Migratable Memory, MPASM, MPLIB, MPLINK, MPSIM, PICkit, PICDEM, PICDEM.net, PICtail, PowerCal, PowerInfo, PowerMate, PowerTool, rLAB, rPIC, Select Mode, SmartSensor, SmartTel and Total Endurance are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

Serialized Quick Turn Programming (SQTP) is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2004, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

**QUALITY MANAGEMENT SYSTEM**  
**CERTIFIED BY DNV**  
**== ISO/TS 16949:2002 ==**

*Microchip received ISO/TS-16949:2002 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona and Mountain View, California in October 2003. The Company's quality system processes and procedures are for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.*



## WORLDWIDE SALES AND SERVICE

### AMERICAS

#### Corporate Office

2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7200  
Fax: 480-792-7277  
Technical Support: 480-792-7627  
Web Address: <http://www.microchip.com>

#### Atlanta

3780 Mansell Road, Suite 130  
Alpharetta, GA 30022  
Tel: 770-640-0034  
Fax: 770-640-0307

#### Boston

2 Lan Drive, Suite 120  
Westford, MA 01886  
Tel: 978-692-3848  
Fax: 978-692-3821

#### Chicago

333 Pierce Road, Suite 180  
Itasca, IL 60143  
Tel: 630-285-0071  
Fax: 630-285-0075

#### Dallas

4570 Westgrove Drive, Suite 160  
Addison, TX 75001  
Tel: 972-818-7423  
Fax: 972-818-2924

#### Detroit

Tri-Atira Office Building  
32255 Northwestern Highway, Suite 190  
Farmington Hills, MI 48334  
Tel: 248-538-2250  
Fax: 248-538-2260

#### Kokomo

2767 S. Albright Road  
Kokomo, IN 46902  
Tel: 765-864-8360  
Fax: 765-864-8387

#### Los Angeles

18201 Von Karman, Suite 1090  
Irvine, CA 92612  
Tel: 949-263-1888  
Fax: 949-263-1338

#### San Jose

1300 Terra Bella Avenue  
Mountain View, CA 94043  
Tel: 650-215-1444  
Fax: 650-961-0286

#### Toronto

6285 Northam Drive, Suite 108  
Mississauga, Ontario L4V 1X5, Canada  
Tel: 905-673-0699  
Fax: 905-673-6509

### ASIA/PACIFIC

#### Australia

Suite 22, 41 Rawson Street  
Epping 2121, NSW  
Australia  
Tel: 61-2-9868-6733  
Fax: 61-2-9868-6755

#### China - Beijing

Unit 706B  
Wan Tai Bei Hai Bldg.  
No. 6 Chaoyangmen Bei Str.  
Beijing, 100027, China  
Tel: 86-10-85282100  
Fax: 86-10-85282104

#### China - Chengdu

Rm. 2401-2402, 24th Floor,  
Ming Xing Financial Tower  
No. 88 TIDU Street  
Chengdu 610016, China  
Tel: 86-28-86766200  
Fax: 86-28-86766599

#### China - Fuzhou

Unit 28F, World Trade Plaza  
No. 71 Wusi Road  
Fuzhou 350001, China  
Tel: 86-591-7503506  
Fax: 86-591-7503521

#### China - Hong Kong SAR

Unit 901-6, Tower 2, Metroplaza  
223 Hing Fong Road  
Kwai Fong, N.T., Hong Kong  
Tel: 852-2401-1200  
Fax: 852-2401-3431

#### China - Shanghai

Room 701, Bldg. B  
Far East International Plaza  
No. 317 Xian Xia Road  
Shanghai, 200051  
Tel: 86-21-6275-5700  
Fax: 86-21-6275-5060

#### China - Shenzhen

Rm. 1812, 18/F, Building A, United Plaza  
No. 5022 Binhe Road, Futian District  
Shenzhen 518033, China  
Tel: 86-755-82901380  
Fax: 86-755-8295-1393

#### China - Shunde

Room 401, Hongjian Building, No. 2  
Fengxiangnan Road, Ronggui Town, Shunde  
District, Foshan City, Guangdong 528303, China  
Tel: 86-757-28395507 Fax: 86-757-28395571

#### China - Qingdao

Rm. B505A, Fullhope Plaza,  
No. 12 Hong Kong Central Rd.  
Qingdao 266071, China  
Tel: 86-532-5027355 Fax: 86-532-5027205

#### India

Divyasree Chambers  
1 Floor, Wing A (A3/A4)  
No. 11, O'Shaughnessy Road  
Bangalore, 560 025, India  
Tel: 91-80-2290061 Fax: 91-80-2290062

#### Japan

Benex S-1 6F  
3-18-20, Shinyokohama  
Kohoku-Ku, Yokohama-shi  
Kanagawa, 222-0033, Japan  
Tel: 81-45-471- 6166 Fax: 81-45-471-6122

#### Korea

168-1, Youngbo Bldg. 3 Floor  
Samsung-Dong, Kangnam-Ku  
Seoul, Korea 135-882  
Tel: 82-2-554-7200 Fax: 82-2-558-5932 or  
82-2-558-5934

#### Singapore

200 Middle Road  
#07-02 Prime Centre  
Singapore, 188980  
Tel: 65-6334-8870 Fax: 65-6334-8850

#### Taiwan

Kaohsiung Branch  
30F - 1 No. 8  
Min Chuan 2nd Road  
Kaohsiung 806, Taiwan  
Tel: 886-7-536-4818  
Fax: 886-7-536-4803

#### Taiwan

Taiwan Branch  
11F-3, No. 207  
Tung Hua North Road  
Taipei, 105, Taiwan  
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

### EUROPE

#### Austria

Durisolstrasse 2  
A-4600 Wels  
Austria  
Tel: 43-7242-2244-399  
Fax: 43-7242-2244-393

#### Denmark

Regus Business Centre  
Lautrup hof 1-3  
Ballerup DK-2750 Denmark  
Tel: 45-4420-9895 Fax: 45-4420-9910

#### France

Parc d'Activite du Moulin de Massy  
43 Rue du Saule Trapu  
Batiment A - 1er Etage  
91300 Massy, France  
Tel: 33-1-69-53-63-20  
Fax: 33-1-69-30-90-79

#### Germany

Steinheilstrasse 10  
D-85737 Ismaning, Germany  
Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

#### Italy

Via Quasimodo, 12  
20025 Legnano (MI)  
Milan, Italy  
Tel: 39-0331-742611  
Fax: 39-0331-466781

#### Netherlands

P. A. De Biesbosch 14  
NL-5152 SC Drunen, Netherlands  
Tel: 31-416-690399  
Fax: 31-416-690340

#### United Kingdom

505 Eskdale Road  
Winnersh Triangle  
Wokingham  
Berkshire, England RG41 5TU  
Tel: 44-118-921-5869  
Fax: 44-118-921-5820